

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	777	257/467.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/03 09:04
L2	58	kim-sarah-e.inv.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/03 09:12
L3	53	list-r-scott.inv.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/03 09:13
L4	24	maveety-james-g.inv.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/03 09:14
L5	0	vu-quat-t.inv.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/03 09:14
L6	35	vu-quat-t.inv.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/03 09:17
L7	31	myers-alan-m.inv.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/03 09:17
S1	2	"5420753".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/01 13:43

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S2	51	(heat adj generating adj (ic or die or chip or (integrated adj circuit))) and (cooling adj (ic or die or chip or (integrated adj circuit)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/02 06:34
S3	11	(heat adj dissipating adj (ic or die or chip or (integrated adj circuit))) and (cooling adj (ic or die or chip or (integrated adj circuit)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/02 06:41
S4	98	(heat adj dissipat\$3 adj (ic or die or chip or (integrated adj circuit))) and (cooling adj (ic or die or chip or (integrated adj circuit)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/02 08:45
S5	370	(heat adj generat\$3 adj (ic or die or chip or (integrated adj circuit))) and (cooling adj (ic or die or chip or (integrated adj circuit)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/02 08:46
S6	37	(cooling adj (ic or die or chip or (integrated adj circuit))) and electroosmotic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/02 07:00
S7	20	(dissipat\$3 adj (ic or die or chip or (integrated adj circuit))) and electroosmotic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/02 07:00
S8	14	(generat\$3 adj (ic or die or chip or (integrated adj circuit))) and electroosmotic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/02 07:01
S9	133	(heat adj dissipat\$3 adj (ic or die or chip or (integrated adj circuit))) and (cool\$3 adj (ic or die or chip or (integrated adj circuit)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/02 08:45

EAST Search History

S10	496	(heat adj generat\$3 adj (ic or die or chip or (integrated adj circuit))) and (cool\$3 adj (ic or die or chip or (integrated adj circuit)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/02 08:46
S11	17	(heat adj generat\$3 adj package) and (cool\$3 adj package)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/02 08:46